SDAS277 - JANUARY 1995

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout
- Inverting-Logic Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), Standard Plastic (N) and Ceramic (J) 300-mil DIPs, and Ceramic Flat (W) Packages

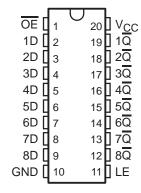
description

These octal D-type transparent latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

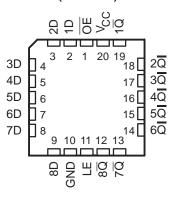
While the latch-enable (LE) input is high, outputs (\overline{Q}) respond to the data (D) inputs. When LE is low, the outputs are latched to retain the data that was set up.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

SN54ALS580B . . . J OR W PACKAGE SN74ALS580B, SN74AS580 . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS580B . . . FK PACKAGE (TOP VIEW)



OE does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54ALS580B is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS580B and SN74AS580 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	L
L	Н	L	Н
L	L	Χ	\overline{Q}_0
Н	Χ	Χ	Z

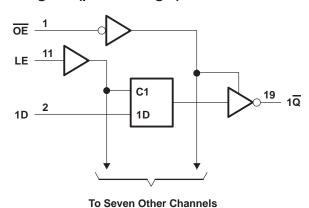
SN54ALS580B, SN74ALS580B, SN74AS580 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

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logic symbol†

OE ΕN 11 LE > C1 2 19 1D 1Q 1D 3 18 2<u>Q</u> 2D 17 4 3D 3Q 16 5 4D 4Q 15 6 5D 5Q 7 14 6D 6Q 8 13 7D 7Q 9 12 8D 8Q

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54ALS580B	–55°C to 125°C
SN74ALS580B	0°C to 70°C
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SNS	54ALS58	0B	SN7	'4ALS58	0B	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-1			-2.6	mA
lOL	Low-level output current			12			24	mA
t _W	Pulse duration, LE high	15			15			ns
t _{su}	Setup time, data before LE↓	20			10			ns
th	Hold time, data after LE↓	12			10			ns
TA	Operating free-air temperature	-55		125	0		70	°C

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		and Tions	SN5	4ALS58	0B	SN7				
PARAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		VCC -2	2			
∨он	V 45V	I _{OH} = -1 mA	2.4	3.3					V	
	V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
V	V 45V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V	
VOL	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V	
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
lozL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ	
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
lіН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.13			-0.1	mA	
I _O ‡	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-20		-112	-30		-112	mA	
		Outputs high		10	17		10	17	_	
ICC	V _{CC} = 5.5 V	Outputs low		16	26		16	26	mA	
		Outputs disabled		17	29		17	29		

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54AL	S580B	SN74AL	S580B	
			MIN	MAX	MIN	MAX	
tPLH	6	Ια	3	26	3	18	
^t PHL	D	Q	3	15	3	14	ns
tPLH			8	29	6	22	
^t PHL	LE	Q	4	22	6	21	ns
^t PZH	ŌĒ	ā	4	25	3	18	
t _{PZL}	OE	Q	4	21	4	18	ns
^t PHZ	ŌĒ	ĪQ	2	12	1	10	20
^t PLZ	OE	γ	3	22	1	15	ns

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

SN54ALS580B, SN74ALS580B, SN74AS580 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SDAS277 - JANUARY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN74AS580	0°C to 70°C
Storage temperature range	

recommended operating conditions

		SN	174AS58	0	
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			8.0	V
ІОН	High-level output current			-15	mA
lOL	Low-level output current			48	mA
t _W *	Pulse duration, LE high	2			ns
t _{su} *	Setup time, data before LE↓	2			ns
th*	Hold time, data after LE↓	3			ns
TA	Operating free-air temperature	0		70	°C

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN	174AS58	0		
PARAMETER	TEST CONDI	TIONS	MIN	TYP‡	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{ } = -18 \text{ mA}$			-1.2	V	
V.	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	!		.,	
VOH	$V_{CC} = 4.5 V,$	$I_{OH} = -15 \text{ mA}$	2.4	3.3		V	
V _{OL}	$V_{CC} = 4.5 V,$	I _{OL} = 48 mA		0.33	0.5	V	
I _{OZH}	$V_{CC} = 5.5 V,$	V _O = 2.7 V			50	μΑ	
l _{OZL}	$V_{CC} = 5.5 V,$	V _O = 0.4 V			-50	μΑ	
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1	mA	
lін	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20	μΑ	
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.4 V			-0.5	mA	
IO§	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-30		-112	mA	
		Outputs high		62	100		
ICC	V _{CC} = 5.5 V	Outputs low		65	106	106 mA	
		Outputs disabled		71	115		

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

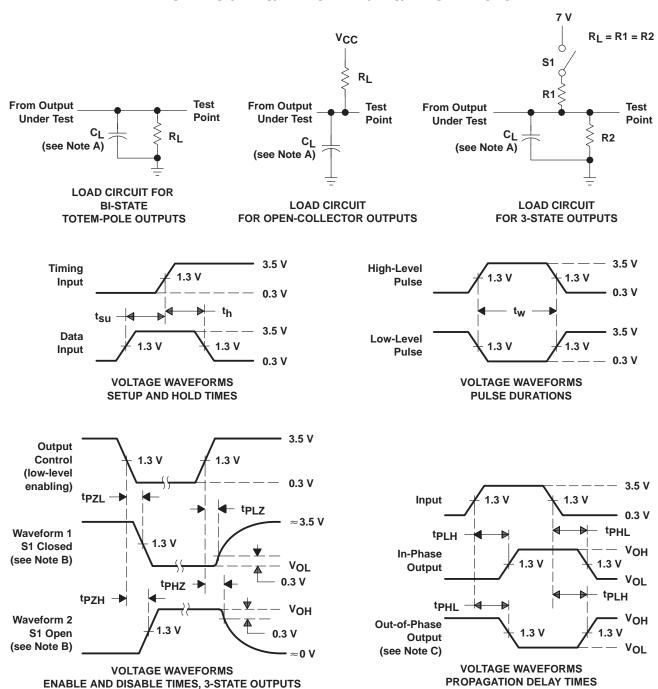
SN54ALS580B, SN74ALS580B, SN74AS580 OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS SDAS277 – JANUARY 1995

switching characteristics (see Figure 1)

PARAMETER	FROM TO (OUTPUT)			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω, T_A = MIN to MAX † SN74AS580			
			MIN	MAX			
^t PLH	D	ĪQ	3	7.5			
^t PHL	В	ά	3	7	ns		
t _{PLH}	LE	ĪQ	5	9			
^t PHL	LE	Q	4	8	ns		
^t PZH	ŌĒ	Q	2	6.5			
t _{PZL}	OE .	Q	4	9.5	ns		
^t PHZ	ŌĒ	ā	2	6.5	ne		
^t PLZ	OE .		2	7	ns		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_{\Gamma} = t_{f} = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84012022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8401202RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
8401202SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN54ALS580BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SN74ALS580BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS580BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS580BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS580BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS580BN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS580BNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS580BNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS580BNSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS580BNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS580DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74AS580DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74AS580N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SNJ54ALS580BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS580BJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54ALS580BW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

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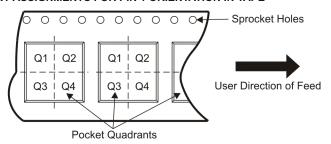
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

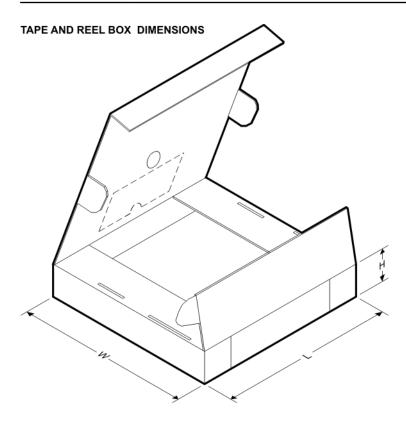
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS580BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS580BNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS580BDWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS580BNSR	SO	NS	20	2000	346.0	346.0	41.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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